

# Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 8290	Ablestik 8290	Same BOM
Wire type	Pd Coated Copper	Pd Coated Copper	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

# Qualification Results Summary for Copper Wire in LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	Result
Temperature/Humidity/Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	PASS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

\*Preconditioned per JEDEC/IPC J-STD-020

# Test Correlation Report

FG Part Number  
ADP1877ACPZ-R7

Test Correlation Status  
Pass